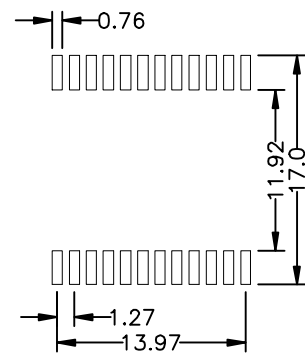
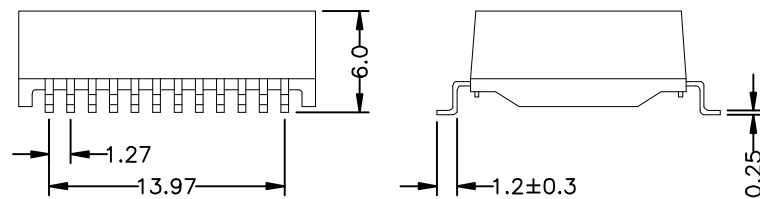
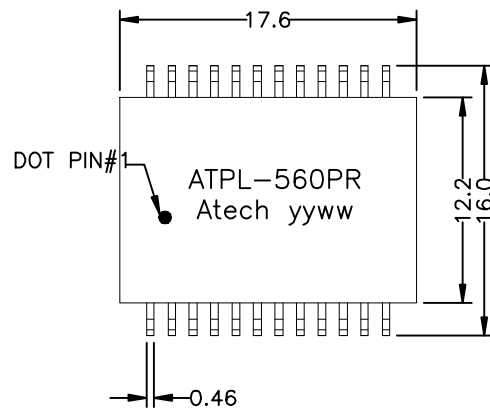
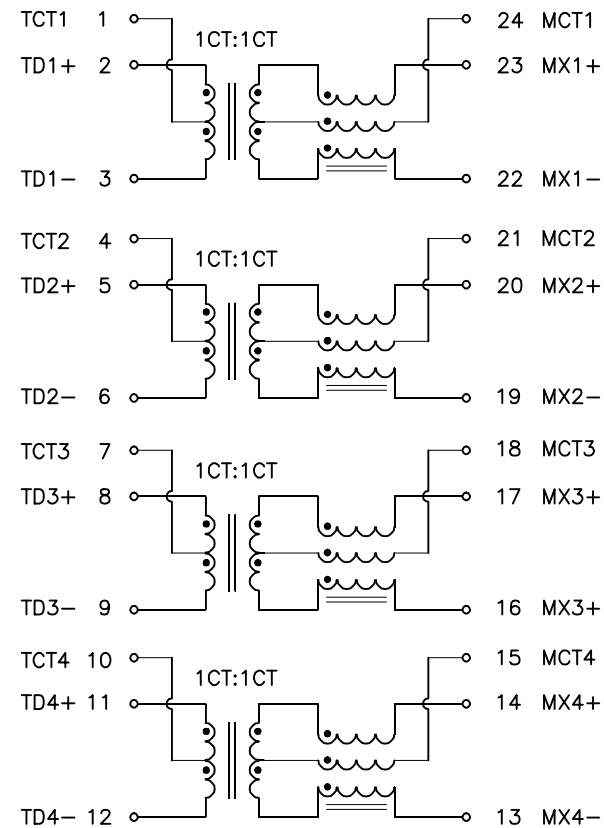




SUGGESTED PAD LAYOUT

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE $\pm 0.25\text{mm}$



								TITLE 10G BASE-T	
								PoE+ TRANSFORMER	
								DWG. NO. ATPL-560PR	
	RELEASE	08/02/2022	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 of 2
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 08/02/22	P/N:	DRAW SHIRLEY	
REVISIONS									

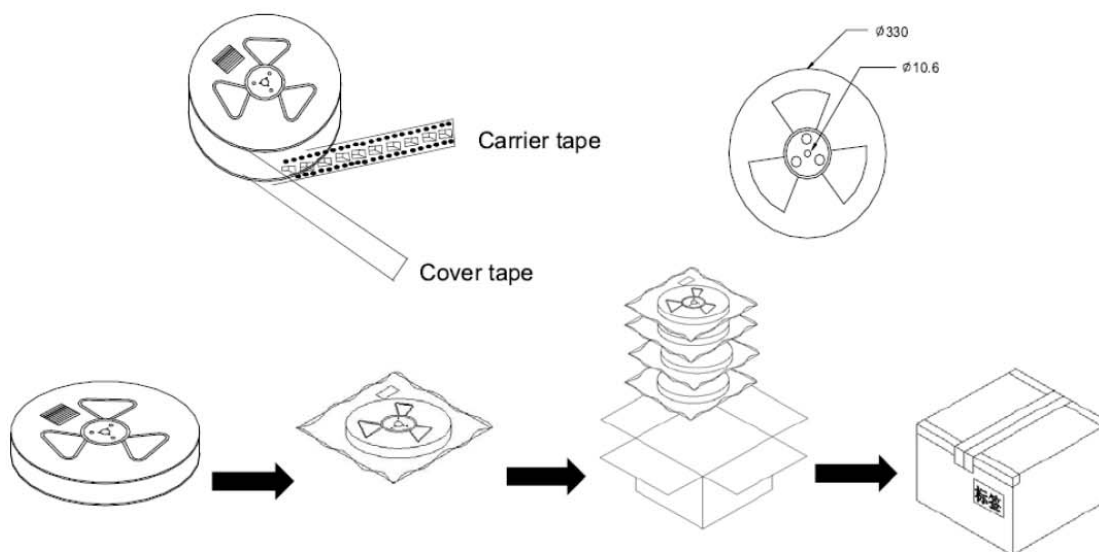
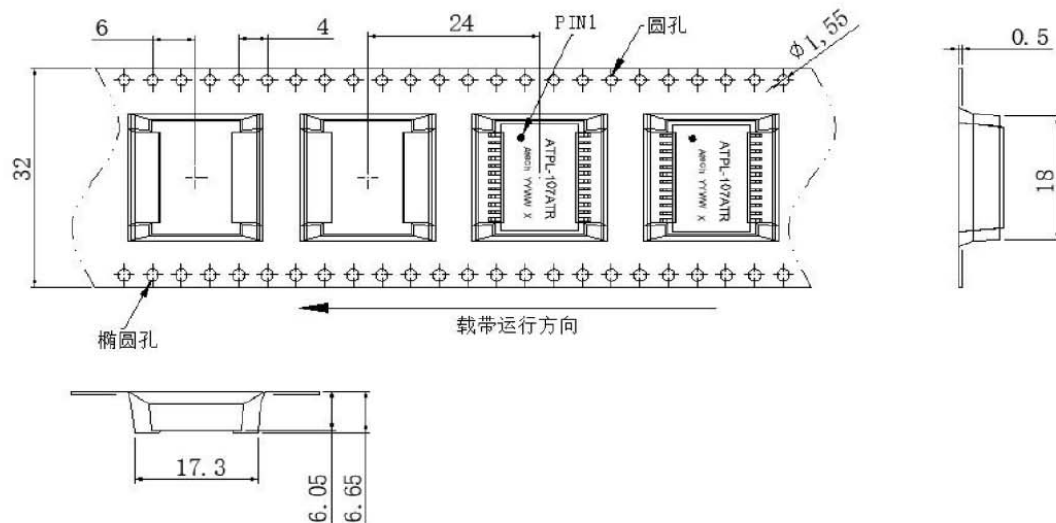
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS @25°C :

1. INSULATION HI-POT : 1500 Vrms/1mA ,60Sec.
2. TURN RATIO ($\pm 5\%$) : 1CT : 1CT
3. DCR : 1.0 Ω MAX.
4. LEAKAGE INDUCTANCE (@100kHz, 0.2Vrms) : 0.5uH MAX.
5. OCL : : (@100kHz, 0.1Vrms with 10.8mA DC BIAS) : 120uH MIN.
6. INSERTION LOSS : @1MHz:-0.8dB MAX. @20MHz:-0.8dB MAX. @50MHz:-1.0dB MAX.
@200MHz:-1.2dB MAX. @400MHz:-2.0dB MAX. @500MHz:-3.0dB MAX.
7. RETURN LOSS : @1MHz:-20dB MIN. @100MHz:-20dB MIN. @200MHz:-18dB MIN.
@300MHz:-15dB MIN. @400MHz:-10dB MIN. @500MHz:-8dB MIN.
8. CROSS TALK : @1MHz:-34dB MIN. @350MHz:-23dB MIN. @500MHz:-23dB MIN.
9. REFLECTED CM TO DIFF CONVERSION (REF) : @50MHz:-30dB MIN. @100MHz:-27dB MIN.
@200MHz:-24dB MIN. @300MHz:-22dB MIN.
@400MHz:-21dB MIN. @500MHz:-20dB MIN.
10. REFLECTED DIFF TO CM CONVERSION (REF) : @1MHz:-48dB MIN. @100MHz:-33dB MIN.
@400MHz:-24dB MIN. @500MHz:-24dB MIN.
11. CM TO DM CONVERSION (REF) : @50MHz:-40dB MIN. @100MHz:-35dB MIN.
@200MHz:-30dB MIN. @300MHz:-22dB MIN.
@400MHz:-17dB MIN. @500MHz:-17dB MIN.
12. CM TO CM ATTENUATION : @1MHz:-22dB MIN. @500MHz:-20dB MIN. @800MHz:-20dB MIN.
@1000MHz:-17dB MIN.
13. Suitable for End-span PoE applications with 720mA current capability
14. IEEE802.3an & 802.3bt COMPLIANT PERFORMANCE
15. OPERATING Temperature RANGE : 0°C~+70°C
16. Storage temperature : -25°C to +125°C

								TITLE 10G BASE-T PoE+ TRANSFORMER	
								DWG. NO. ATPL-560PR	
	RELEASE	08/02/2022	SHIRLEY	BETTY	BETTY	UNITS: M/M		SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 08/02/22		P/N:	
REVISIONS						08/02/22		DRAW SHIRLEY	
								SHEET 2 OF 2	

3. Package:



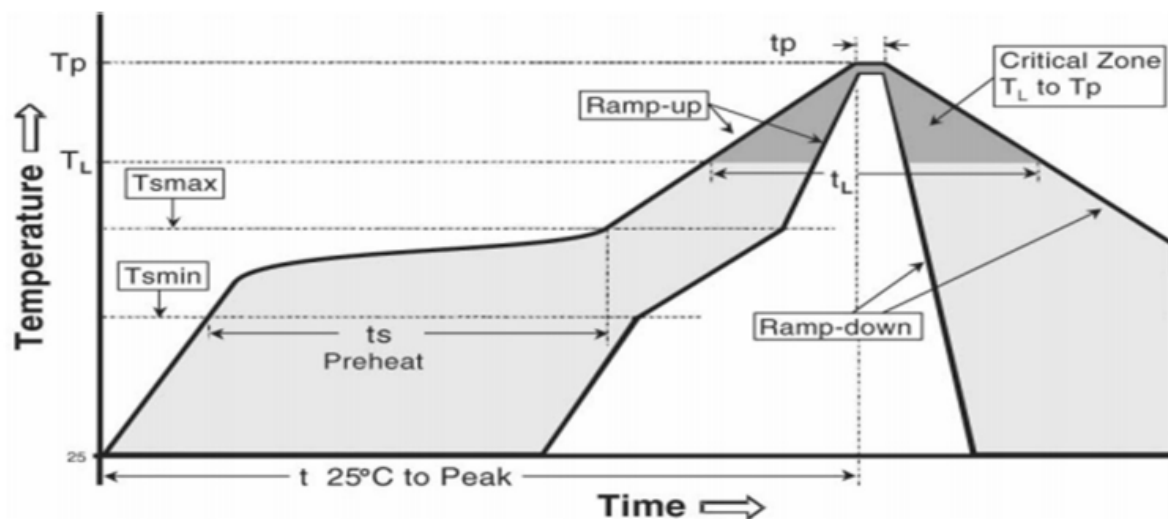
Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 24 PIN Series	400	400x6=2400		1.45

Remarks:

- 1) Packing Level & Storage Condition based on MSL1
- 2) ESD package
- 3) Parts packaging meet EIA-481 standard (pull 0.26N~1.3N)

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmmax)	150°C	200°C
Time (Tsmmin to Tsmmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max